1 Package summary

Table 1. Package summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>package length</td>
<td>-</td>
<td>14</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
<td>-</td>
<td>14</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
<td>-</td>
<td>1.37</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>nominal pitch</td>
<td>-</td>
<td>0.8</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>269</td>
<td>-</td>
<td>mm</td>
</tr>
</tbody>
</table>
Figure 1. Package outline LFBGA269 (sot1989-1)
NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

Figure 2. Package outline note LFBGA269 (sot1989-1)
3 Soldering

Figure 3. Reflow soldering footprint part1 for LFBGA269 (SOT1989-1)
PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

Figure 4. Reflow soldering footprint part2 for LFBGA269 (SOT1989-1)
Figure 5. Reflow soldering footprint part3 for LFBGA269 (SOT1989-1)
4 Legal information

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SOT1989-1

LFBGA269, low-profile fine-pitch ball grid array package, 269 terminals, 0.8 mm pitch, 14 mm x 14 mm x 1.37 mm body

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